



## 40V N&P-Channel Trench Power MOSFET

### General Description

The SJD40NP270 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a wide variety of applications.

### Features

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handling capability
- Lead free product is acquired

### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

### Key Performance Parametes

Parameter	Value	Value	Unit
$V_{DS}$	40	-40	V
$R_{DS(ON\_TYP)}$	19	11.3	mΩ
$I_D$	26	-48	A
$Q_G$	15.5	60	nC



### Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD40NP270	SJD40NP270	TO-252-4L	Tape	\	\	2500 Pcs

**Table 1. Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	N Limit	P Limit	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0V$ )	40	-40	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0V$ )	$\pm 20$	$\pm 20$	V
$I_D$	Drain Current-Continuous( $T_C=25^\circ\text{C}$ )	26	-48	A
	Drain Current-Continuous( $T_C=100^\circ\text{C}$ )	17	-31	A
$I_{DM}$ (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	104	-192	A
$P_D$	Maximum Power Dissipation( $T_C=25^\circ\text{C}$ )	28	60	W
	Maximum Power Dissipation( $T_C=100^\circ\text{C}$ )	11	24	W
$E_{AS}$	Avalanche energy (Note 2)	30	272	mJ
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 150		$^\circ\text{C}$

**Table 2. Thermal Characteristic**

Symbol	Parameter	N Limit	P Limit	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	4.4	2.1	$^\circ\text{C/W}$



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**Table 3. N-Channel Electrical Characteristics ( $T_J=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	40			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V T <sub>J</sub> =25℃			1	μA
		V <sub>DS</sub> =40V, V <sub>GS</sub> =0V T <sub>J</sub> =125℃			100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1		2.5	V
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =10A				S
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =3A T <sub>J</sub> =25℃		19	24.7	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =4.5V, I <sub>D</sub> =2A T <sub>J</sub> =25℃		21.1	28.1	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1.0MHz		728		pF
C <sub>oss</sub>	Output Capacitance			51.6		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			42		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		3.4		Ω
Switching Parameters						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =20V, R <sub>L</sub> =6.7Ω, R <sub>GEN</sub> =3Ω		4.5		nS
t <sub>r</sub>	Turn-on Rise Time			2.2		nS
t <sub>d(off)</sub>	Turn-Off Delay Time			28.4		nS
t <sub>f</sub>	Turn-Off Fall Time			4.6		nS
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =20V, I <sub>D</sub> =3A		15.5		nC
Q <sub>gs</sub>	Gate-Source Charge			2.32		nC
Q <sub>gd</sub>	Gate-Drain Charge			1.84		nC
Source-Drain Diode Characteristics						
I <sub>SD</sub>	Source-Drain Current (Body Diode)				26	A
V <sub>SD</sub>	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =3A			1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =3A, dI/dt=500A/μs		8.9		ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =3A, dI/dt=500A/μs		2.7		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.EAS condition:  $T_J=25^{\circ}\text{C}, V_{DD}=30V, V_G=10V, R_g=25\Omega, L=0.5mH$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



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### N-Channel Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

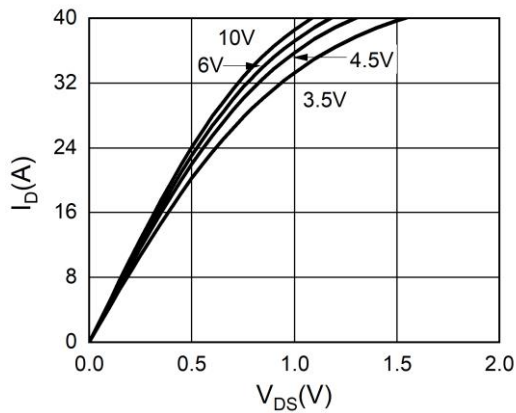


Figure 2. Transfer Characteristics

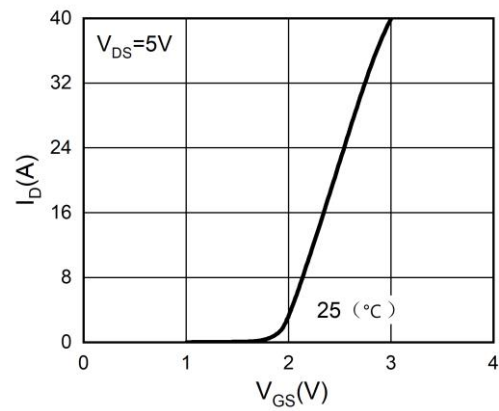


Figure 3. Power Dissipation

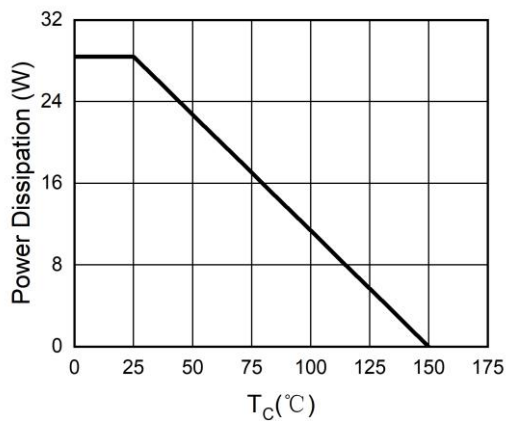


Figure 4. Drain Current

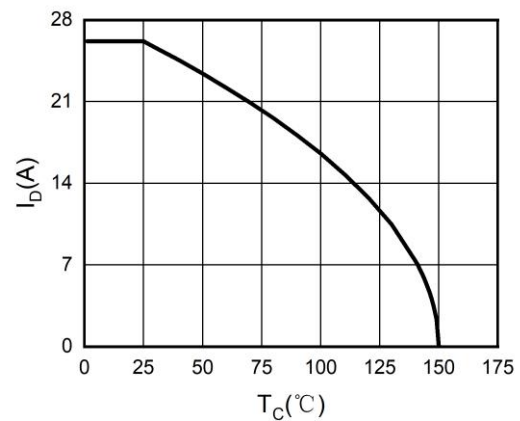


Figure 5.  $BV_{DSS}$  vs Junction Temperature

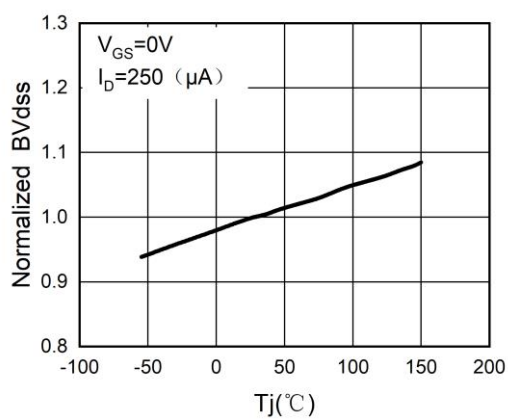
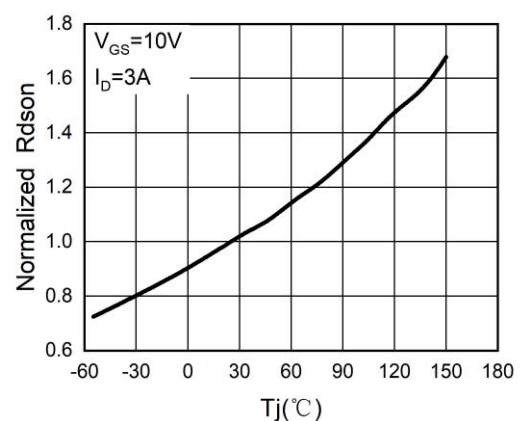
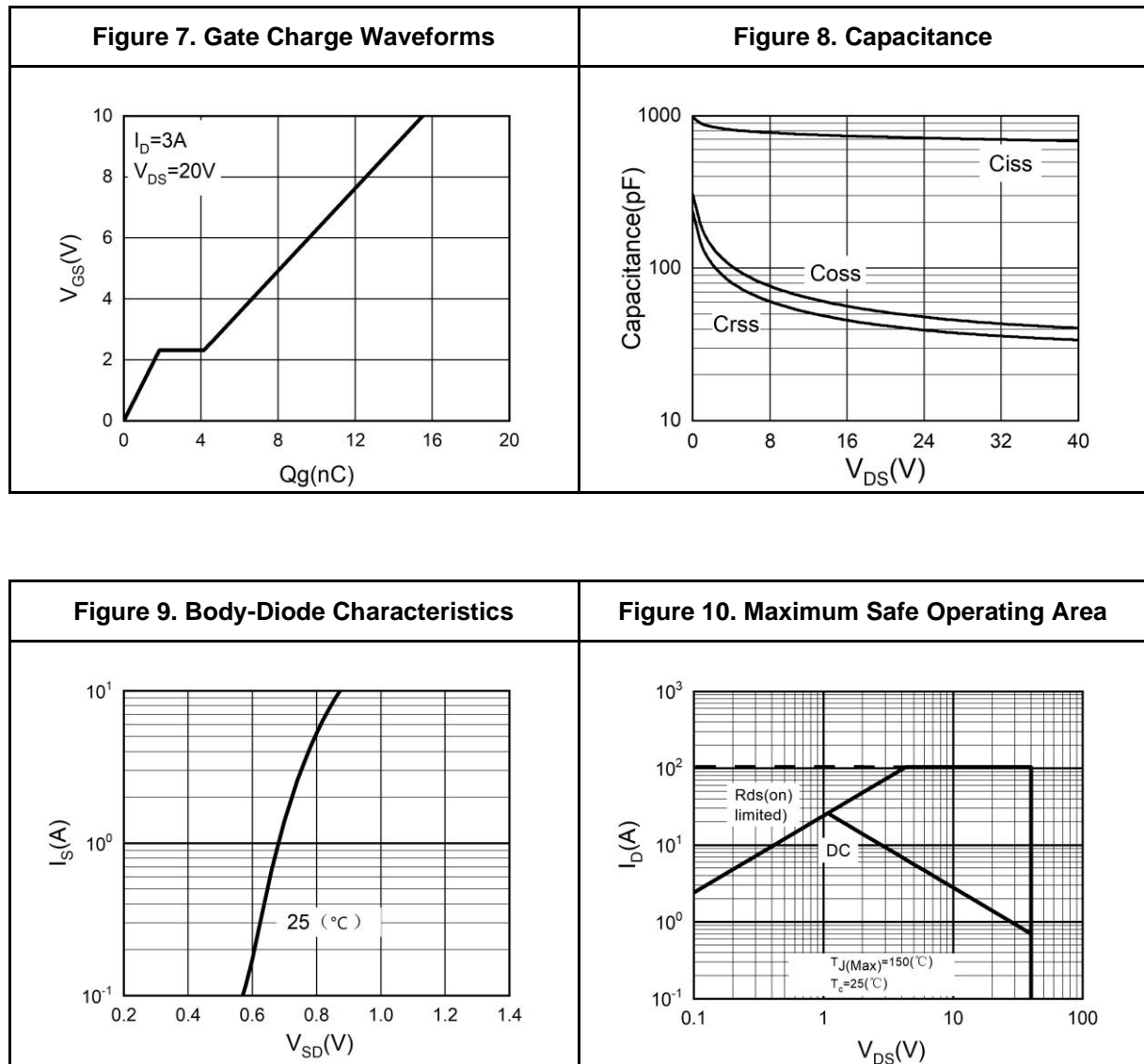


Figure 6.  $R_{DS(ON)}$  vs Junction Temperature





## N-Channel Typical Electrical And Thermal Characteristics (Curves)





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**Table 4. P-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-40			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V T <sub>J</sub> =25℃			-1	μA
		V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V T <sub>J</sub> =125℃			-100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1		-2.5	V
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-5A		30		S
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-15A T <sub>J</sub> =25℃		11.3	14.7	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A T <sub>J</sub> =25℃		15.2	20.2	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V, f=1.0MHz		3241		pF
C <sub>oss</sub>	Output Capacitance			228		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			205		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1.0MHz		4.5		Ω
Switching Parameters						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-20V, R <sub>L</sub> =1Ω, R <sub>GEN</sub> =3Ω		18		nS
t <sub>r</sub>	Turn-on Rise Time			4.8		nS
t <sub>d(off)</sub>	Turn-Off Delay Time			88.8		nS
t <sub>f</sub>	Turn-Off Fall Time			26.4		nS
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-20V, I <sub>D</sub> =-15A		60		nC
Q <sub>gs</sub>	Gate-Source Charge			8.6		nC
Q <sub>gd</sub>	Gate-Drain Charge			13.9		nC
Source-Drain Diode Characteristics						
I <sub>SD</sub>	Source-Drain Current (Body Diode)				-48	A
V <sub>SD</sub>	Forward on Voltage (Note 3)	V <sub>GS</sub> =0V, I <sub>S</sub> =-15A			-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =-15A, dI/dt=-100A/μs		17.3		ns
Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =-15A, dI/dt=-100A/μs		9.5		nC

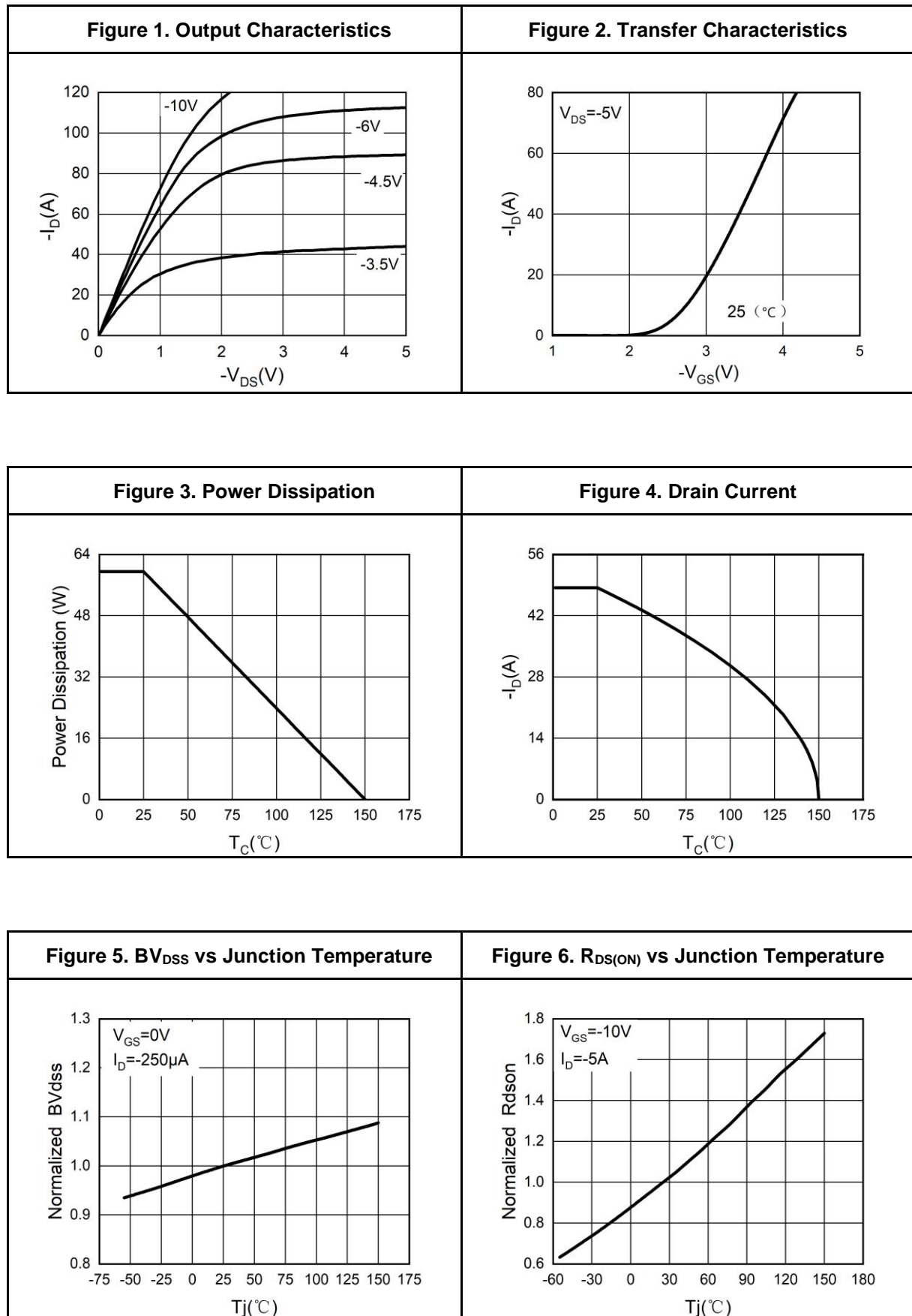
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.EAS condition:  $T_J=25^\circ\text{C}, V_{DD}=-30V, V_G=-10V, R_g=25\Omega, L=0.5\text{mH}$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

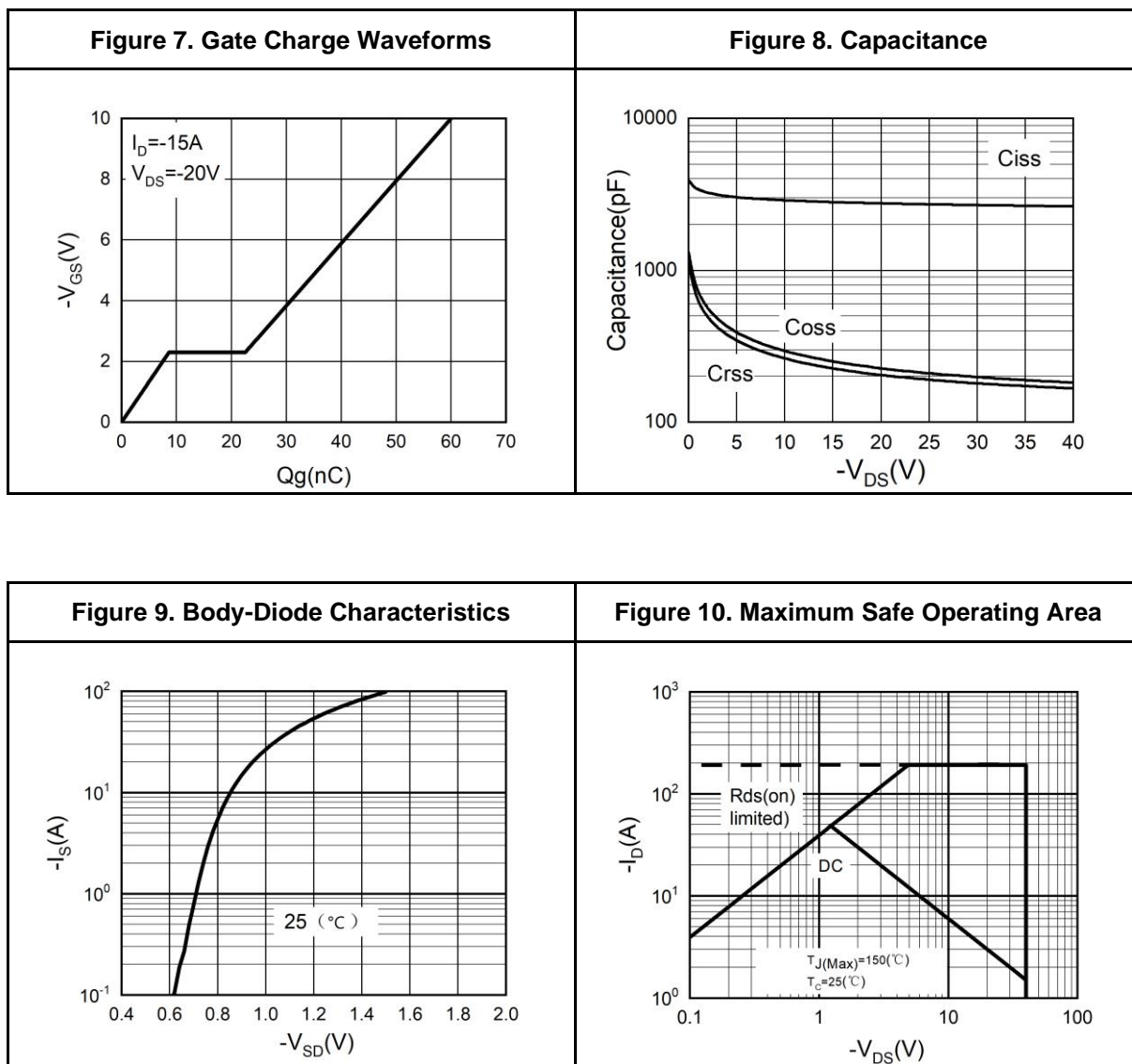


## P-Channel Typical Electrical And Thermal Characteristics (Curves)



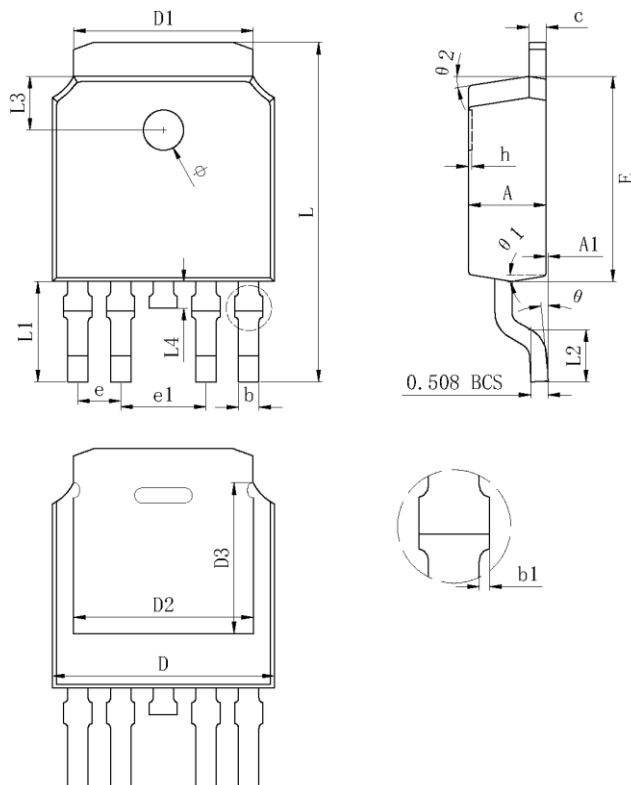


## P-Channel Typical Electrical And Thermal Characteristics (Curves)





## TO-252-4L Package Information



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.550	0.600	0.650
b1	0.000		0.120
c (电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	5.346 REF		
D3	4.490 REF		
E	6.000	6.100	6.200
e	1.270 TYP		
e1	2.540 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.988 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.700	0.800	0.900
$\phi$	1.100	1.200	1.300
$\theta$	0°		
$\theta 1$	9° TYP		
$\theta 2$	9° TYP		



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### Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

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